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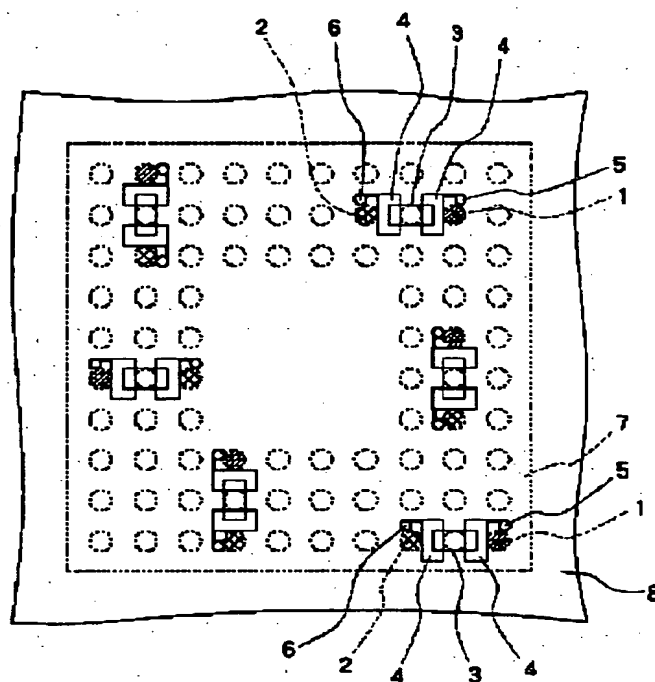
APPLICATION DATE : 19-02-96
APPLICATION NUMBER : 08030847

APPLICANT : CANON INC;

INVENTOR : TAKEUCHI YASUSHI;

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TITLE : SEMICONDUCTOR INTEGRATED
CIRCUIT AND PRINTED WIRING
BOARD



ABSTRACT : **PROBLEM TO BE SOLVED:** To reduce electromagnetic wave radiation noise radiated from a printed wiring board mounted with semiconductor integrated circuits such as BGA (ball grid array) and CPS(chip scale package) on the back surface of which are provided with a plurality of connecting pads.

SOLUTION: The distance between a pad 1 for a power supply and a pad 2 for the ground of a BGA chip 7 that make a pair is matched with the distance between the electrodes of a decoupling capacitor 3 mounted on the other side surface of the surface on which the BGA chip 7 is mounted in a printed wiring board 8. Through a through hole 5 for the connection of the power supply and a through hole 6 for the connection of the ground, the pad 1 for the power supply and the pad 2 for the ground are connected to the decoupling capacitor 3.

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